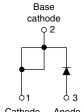


### VS-8ETH03PbF, VS-8ETH03-N3

Vishay Semiconductors

# Hyperfast Rectifier, 8 A FRED Pt®





**TO-220AC** 

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Υ	2
l T	
•	+
	T
01	03
O I	0.3
Cathode	Anode

PRODUCT SUMMARY						
Package	TO-220AC					
I <sub>F(AV)</sub>	8 A					
$V_{R}$	300 V					
V <sub>F</sub> at I <sub>F</sub>	0.83 V					
t <sub>rr</sub> typ.	See Recovery table					
T <sub>J</sub> max.	175 °C					
Diode variation	Single die					

#### **FEATURES**

- · Hyperfast recovery time
- · Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- · Designed and qualified according to JEDEC®-JESD 47
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





HALOGEN **FREE** 

#### **DESCRIPTION / APPLICATIONS**

300 V series are the state of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diodes in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Repetitive peak reverse voltage	$V_{RRM}$		300	V			
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 155 °C	8	۸			
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>C</sub> = 25 °C	100	Α			
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C			

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	$V_{BR}$ , $V_{R}$	I <sub>R</sub> = 100 μA	300	-	-		
Forward voltage	$V_{F}$	I <sub>F</sub> = 8 A	-	1.0	1.25	V	
		I <sub>F</sub> = 8 A, T <sub>J</sub> = 125 °C	-	0.83	1.00		
Poverse leakage current		$V_R = V_R$ rated	-	0.02	20		
Reverse leakage current I <sub>R</sub>		$T_J = 125  ^{\circ}C$ , $V_R = V_R$ rated	-	6.0	200	μΑ	
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 300 V	-	31	-	pF	
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8	-	nH	



# VS-8ETH03PbF, VS-8ETH03-N3

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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>C</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 A, dI_F/dt = -3$	$I_F = 1 \text{ A, } dI_F/dt = -50 \text{ A/}\mu\text{s, } V_R = 30 \text{ V}$		-	35		
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	27	-	ns	
		T <sub>J</sub> = 125 °C	I <sub>F</sub> = 8 A dI <sub>F</sub> /dt = - 200 A/μs V <sub>R</sub> = 200 V	-	40	-		
Peak recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	2.2	-	Α	
		T <sub>J</sub> = 125 °C		-	5.3	-	_ ^	
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	30	-	nC	
		T <sub>J</sub> = 125 °C		-	106	-	IIC	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C	
Thermal resistance, junction to case per leg	R <sub>thJC</sub>		-	1.45	2.5		
Thermal resistance, junction to ambient per leg	R <sub>thJA</sub>	Typical socket mount	-	-	70	°C/W	
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.2	-		
Waight			-	2.0	-	g	
Weight			-	0.07	-	OZ.	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)	
Marking device		Case style TO-220AC		8ETH03			



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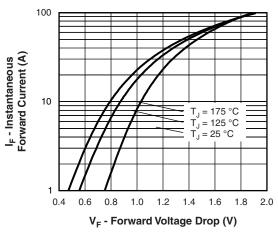


Fig. 1 - Typical Forward Voltage Drop Characteristics

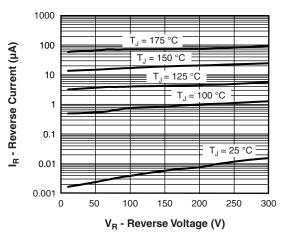


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

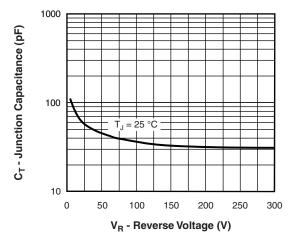


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

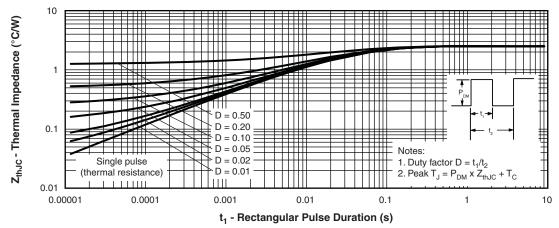


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics



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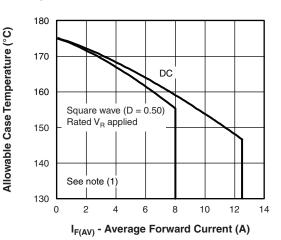


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

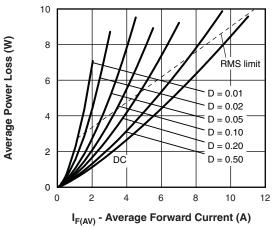


Fig. 6 - Forward Power Loss Characteristics

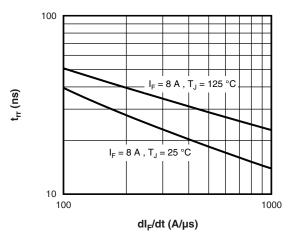


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

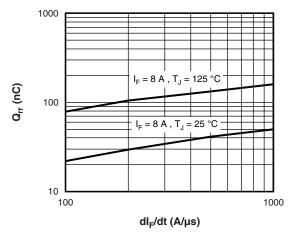


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $\begin{array}{l} \text{(1)} \ \ \text{Formula used:} \ T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \ \text{at} \ (I_{F(AV)}/D) \ (\text{see fig. 6}); \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \ (1 - D); \ I_R \ \text{at} \ V_{R1} = \text{Rated} \ V_R \\ \end{array}$ 

### Vishay Semiconductors

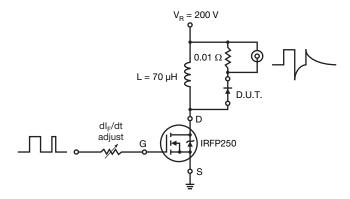
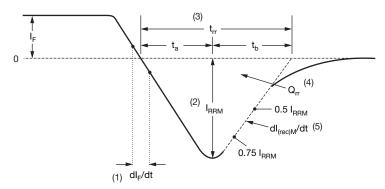


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dI<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_{r}$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{rr}$  area under curve defined by  $\mathbf{t}_{rr}$  and  $\mathbf{I}_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5)  $dI_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

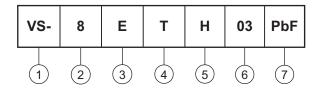
Fig. 10 - Reverse Recovery Waveform and Definitions

## VS-8ETH03PbF, VS-8ETH03-N3

### Vishay Semiconductors

#### **ORDERING INFORMATION TABLE**





1 - Vishay Semiconductors product

2 - Current rating (8 = 8 A)

3 - E = single diode

4 - Package:

T = TO-220

H = hyperfast recovery

6 - Voltage rating (03 = 300 V)

7 - Environmental digit:

PbF = lead (Pb)-free and RoHS-compliant

-N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-8ETH03PbF	50	1000	Antistatic plastic tube				
VS-8ETH03-N3	50	1000	Antistatic plastic tube				

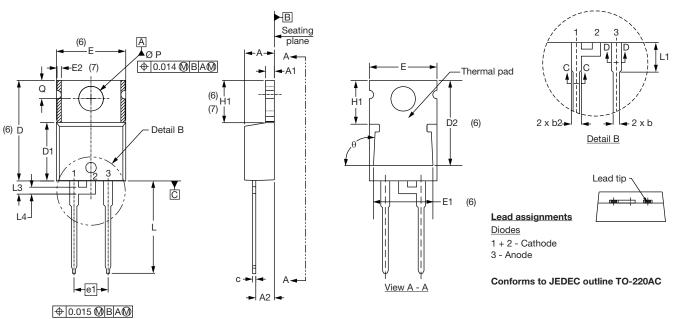
LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?95221</u>					
Part marking information	TO-220ACPbF	www.vishay.com/doc?95224			
Part marking information	TO-220AC-N3	www.vishay.com/doc?95068			



### Vishay Semiconductors

### **TO-220AC**

#### **DIMENSIONS** in millimeters and inches



SYMBOL MILI		IETERS	RS INCHES		NOTES	
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.25	4.65	0.167	0.183		
A1	1.14	1.40	0.045	0.055		
A2	2.56	2.92	0.101	0.115		
b	0.69	1.01	0.027	0.040		
b1	0.38	0.97	0.015	0.038	4	
b2	1.20	1.73	0.047	0.068		
b3	1.14	1.73	0.045	0.068	4	
С	0.36	0.61	0.014	0.024		
c1	0.36	0.56	0.014	0.022	4	
D	14.85	15.25	0.585	0.600	3	
D1	8.38	9.02	0.330	0.355		
D2	11.68	12.88	0.460	0.507	6	
Е	10.11	10.51	0.398	0.414	3, 6	

SYMBOL	MILLIM	IETERS	INCHES		NOTES
STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
е	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
L3	1.78	2.13	0.070	0.084	
L4	0.76	1.27	0.030	0.050	2
ØΡ	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	
θ	90° t	o 93°	90° to 93°		

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline

Document Number: 95221 Revision: 07-Mar-11

### **Legal Disclaimer Notice**



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